

**TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT**  
 (Under 37 CFR 1.97(b) or 1.97(c))

Docket No.  
 DC5157PCT1

In Re Application Of: CHENG et. al

Application No.	10/565916	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
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Title: Process for Fabricating Electronic Components Using Liquid Injection Molding

Address to:

Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

**37 CFR 1.97(b)**

1.  The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

**37 CFR 1.97(c)**

2.  The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

the statement specified in 37 CFR 1.97(e);

OR

the fee set forth in 37 CFR 1.17(p).

**TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT**  
 (Under 37 CFR 1.97(b) or 1.97(c))

Docket No.  
 DC5157PCT1

In Re Application: CHENG et. al

Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/1565018			00137		

Title: Process for Fabricating Electronic Components Using Liquid Injection Molding

**Payment of Fee**

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- A check in the amount of \_\_\_\_\_ is attached.
- The Director is hereby authorized to charge and credit Deposit Account No. 04-1520 as described below.
  - Charge the amount of \$ \_\_\_\_\_
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  - Charge any additional fee required.
- Payment by credit card. Form PTO-2038 is attached.

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Christine M. Fitak

*Typed or Printed Name of Person Mailing Certificate*

\*This certificate may only be used if paying by deposit account.

Catherine Brown  
 Signature

Catherine Brown  
 Reg. No. 44,565  
 989-496-1725  
 Senior IP Attorney  
 Mail Number C01232  
 P.O. Box 994  
 2200 W. Salzburg Road  
 Midland, MI 48686-0994  
 UNITED STATES OF AMERICA

Dated: Jan 24, 2006

CustomerNumber 00137

CC:

INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)			Docket Number (Optional) DC5157PCT1		Application Number 107565916	
			Applicant(s) TAMMY CHENG et al.			
			Filing Date	Group Art Unit		

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		4,293,479	06-Oct-1981	Hanada, et. al.	260	37	
		4,327,369	27-Apr-1982	Kaplan	357	72	
		4,663,397	05-May-1987	Morita, et. al.	525	398	
		4,778,860	18-Oct-1988	Morita	525	431	
		4,880,882	14-Nov-1989	Morita, et. al.	525	446	

## U.S. PATENT APPLICATION PUBLICATIONS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		2001/0040283 A1	15-Nov-2001	Konishi, et. al.	257	687	

## FOREIGN PATENT DOCUMENTS

REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
	WO 2003/041130 A2	20-Sep-2002	EP				
	WO 2000/047391 A1	17-Aug-2000	EP				
	EP 0 685 508 B1	06-May-1999	EP				
	EP 0 707 042 B1	11-Mar-1998	EP				
	JP 83834/03	25-Mar-2003	JP				

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

		Harper, Charles A., Ed., "Packaging Assembly Process," Packaging and Interconnection Handbook, 2nd ed., pp. 6.66-6.77, McGraw-Hill, New York, 1997.
		Kroschwitz, J., ed., "Electronic Materials," Kirk-Othmer Encyclopedia of Chemical Technology, 4th ed., vol. 9, pp.219-229, John Wiley & Sons, New York, 1994.

EXAMINER	DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<b>INFORMATION DISCLOSURE CITATION</b> <i>(Use several sheets if necessary)</i>				Docket Number (Optional) <b>DC5157PCCT1</b>		Application Number <b>10/565916</b>	
				Applicant(s) <b>TAMMY CHENG</b> et al.		Filing Date 	
<b>U.S. PATENT DOCUMENTS</b>							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		5,387,624	07-Feb-1995	Morita, et. al.	523	220	
		5,492,945	20-Feb-1996	Morita, et. al.	523	212	
		5,691,401	25-Nov-1997	Morita, et. al.	523	435	
		5,933,713	03-Aug-1999	Farnworth	438	127	
<b>U.S. PATENT APPLICATION PUBLICATIONS</b>							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<b>FOREIGN PATENT DOCUMENTS</b>							
REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
<b>OTHER DOCUMENTS</b> <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>							
		Abstract, DE 19801657, July 29, 1999.  Abstract, "The Lead Plastic Chip Carrier - its Reliability and Use." Brodsky, et. al., January 1, 1981.					
		Hmiel, Andrew F., et. al., "A Novel Process for Protecting Wire Bonds from Sweep During Molding.", SEMICON West 2002 Technology Symposium.					
<b>EXAMINER</b>				<b>DATE CONSIDERED</b>			

**EXAMINER:** Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.